

Title (en)
EPITAXIAL METHODS AND STRUCTURES FOR FORMING SEMICONDUCTOR MATERIALS

Title (de)
EPITAXIALVERFAHREN UND STRUKTUREN ZUR BILDUNG VON HALBLEITERMATERIALIEN

Title (fr)
PROCÉDÉS D'ÉPITAXIE ET STRUCTURES ÉPITAXIALES POUR FORMER DES MATÉRIAUX SEMI-CONDUCTEURS

Publication
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Application
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Abstract (en)
[origin: WO2010089623A1] Methods and structures for producing semiconductor materials, substrates and devices with improved characteristics are disclosed. Structures and methods for forming reduced strain structures include forming a plurality of substantially strain relaxed island structures and utilizing such island structures for subsequent further growth of strain relaxed substantial continuous layers of semiconductor material.

IPC 8 full level
H01L 21/205 (2006.01)

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H01L 21/02647 (2013.01 - EP); **H01L 21/0265** (2013.01 - EP); **H01L 21/20** (2013.01 - KR)

Citation (search report)
See references of WO 2010089623A1

Citation (examination)
WO 2009015350 A1 20090129 - SOITEC SILICON ON INSULATOR [FR], et al

Cited by
EP2837763A1; DE102013108848A1

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